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semiconductor device, comprising
semiconductor chip;
thin wires respectively connecting
said semiconductor chip;
wiring board electrically connecting
chip by said metal thin wires
heat spreader equipped with said
wiring board provided thereon
adhesive layer which is provided
surface of said heat spreader and
chip and said wiring board to
encapsulating resin for sealing
wires.

the semiconductor device as claimed
second adhesive layer having the
characteristic as said adhesive layer is provided
surface of said heat spreader.

the semiconductor device as claimed
radiating fin is provided over said
layer.

method of manufacturing a semiconductor

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method of manufacturing a semiconductor

comprising the following steps:

- a step for preparing a heat spreader;
- a step for forming an adhesive layer over a principal surface of said heat spreader;
- a step for forming a semiconductor chip and a wiring board over said adhesive layer;
- a step for connecting electrodes of said semiconductor chip and said wiring board by metal thin wires; and
- a step for sealing at least said metal thin wires with an encapsulating resin.

5. A method of manufacturing a semiconductor device, comprising the following steps:

- a step for preparing a heat spreader;
- a step for forming a first adhesive layer and a second adhesive layer over a principal surface of said heat spreader;
- a step for forming a wiring board over said first adhesive layer;
- a step for forming a semiconductor chip over said adhesive layer;
- a step for connecting electrodes of said semiconductor chip and said wiring board by metal thin wires; and
- a step for sealing said second adhesive layer and part of said semiconductor chip with a first

encapsulating resin and sealing said metal thin wires and said semiconductor chip with a second encapsulating resin after said first encapsulating resin has been cured.

6. The method as claimed in claim 5, wherein said first encapsulating resin and said second encapsulating resin are respectively encapsulating resins different in material from each other.

7. A method of manufacturing a semiconductor device, comprising the following steps:

a step for preparing a heat spreader;

a step for forming a first adhesive layer and a second adhesive layer over a principal surface of said heat spreader;

a step for forming a wiring board over said first adhesive layer;

a step for forming a semiconductor chip over said second adhesive layer;

a step for connecting electrodes of said semiconductor chip and said wiring board by metal thin wires;

a step for sealing said second adhesive layer and part of said semiconductor chip with an encapsulating resin; and

a step for sealing said metal thin wires and said semiconductor chip with said encapsulating resin after

said encapsulating resin has been cured.

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